To our customers,

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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RENESAS

MOS INTEGRATED CIRCUIT

μPD4721

RS-232 LINE DRIVER/RECEIVER AT 3.3 V/5 V

The μPD4721 is a high-breakdown voltage silicon gate CMOS line driver/receiver based on the EIA/TIA-232-E standard. The internal DC/DC converter can switch between multiple voltages, realizing the allowing it to operate with a single +3.3 V or +5 V power supply. It also provides standby function.

This IC incorporates 2 driver circuits and 2 receiver circuits. An RS-232 interface circuit can be easily configured by connecting 5 capacitors externally.

FEATURES

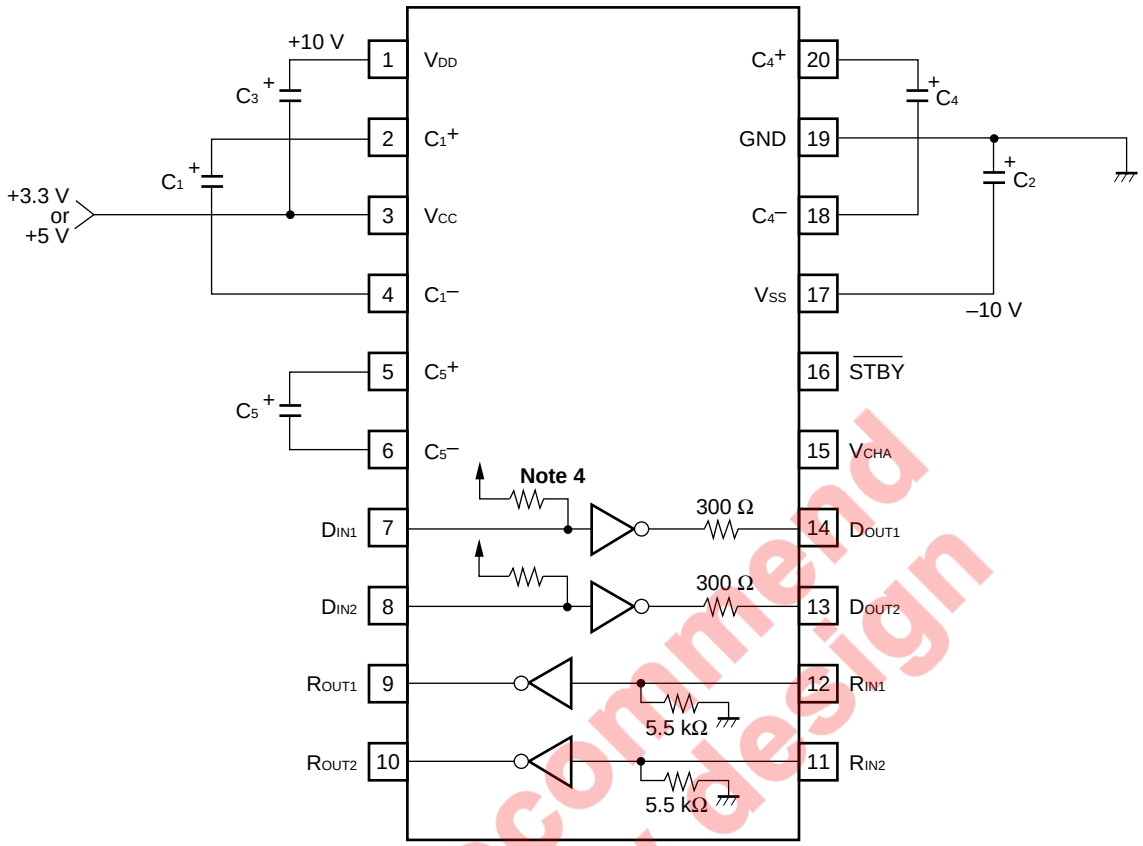
- Conforms to EIA/TIA-232-E (former name, RS-232C) standards
- Selectable +3.3 V/+5 V single power supply (selected by V_{CHA} pin)
- By setting the standby pin to a low level (standby mode), circuit current can be reduced. At such times, the driver output is in a high-impedance state.

ORDERING INFORMATION

Part number	Package
μPD4721GS-GJG	20-pin plastic SSOP (300 mil)

Document No. S12198EJ2V0DS00 (2nd edition)
(Previous No. IC-3279)
Date Published January 1997 N
Printed in Japan

BLOCK DIAGRAM/PIN CONFIGURATION (Top View)



Note 1. V_{DD} and V_{SS} are output pins stepped up internally. These pins should not be loaded directly.

2. Capacitors C_1 to C_5 with a breakdown voltage of 20 V or higher are recommended. And it is recommended to insert the capacitor that is 0.1 μF to 1 μF between V_{CC} and GND.

3. If V_{CHA} is kept low level (in 5 V mode), capacitor C_5 is not necessary.

4. The pull-up resistors at driver input are active resistors.

Truth Table

Driver

$\overline{STBY}$	D_{IN}	D_{OUT}	Remarks
L	×	Z	Standby mode (DC/DC converter is stopped)
H	L	H	Space level output
H	H	L	Mark level output

Receiver

$\overline{STBY}$	R_{IN}	R_{OUT}	Remarks
L	×	H	Standby mode (DC/DC converter is stopped)
H	L	H	Mark level input
H	H	L	Space level input

3 V ↔ 5 V switching Note 5

V_{CHA}	Operating mode
L	5 V mode (double step-up)
H	3 V mode (3 times step-up)

H: high-level, L: low-level, Z: high-impedance, ×: H or L

Note 5. When switching V_{CHA}, standby mode must be selected ($\overline{STBY}$ = L).

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C)

Parameter	Symbol	Ratings	Unit
Supply Voltage (V_{CHA} = L)	V_{CC}	–0.5 to +7.0	V
Supply Voltage (V_{CHA} = H)	V_{CC}	–0.5 to +4.5	V
Driver Input Voltage	D_{IN}	–0.5 to V_{CC} +0.5	V
Receiver Input Voltage	R_{IN}	–30.0 to +30.0	V
Control Input Voltage ($\overline{STBY}$, V_{CHA})	V_{IN}	–0.5 to V_{CC} +0.5	V
Driver Output Voltage	D_{OUT}	–25.0 to +25.0 **Note 6**	V
Receiver Output Voltage	R_{OUT}	–0.5 to V_{CC} +0.5	V
Input Current (D_{IN}, $\overline{STBY}$, V_{CHA})	I_{IN}	±20.0	mA
Operating Ambient Temperature	T_A	–40 to +85	°C
Storage Temperature	T_{stg}	–55 to +150	°C
Total Power Dissipation	P_T	0.5	W

Note 6. Pulse width = 1 ms, duty = 10 % MAX.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage (V_{CHA} = L, 5 V mode)	V_{CC}	4.5	5.0	5.5	V
Supply Voltage (V_{CHA} = H, 3 V mode)	V_{CC}	3.0	3.3	3.6	V
High-Level Input Voltage (D_{IN})	V_{IH}	2.0		V_{CC}	V
Low-Level Input Voltage (D_{IN})	V_{IL}	0		0.8	V
High-Level Input Voltage ($\overline{STBY}$, V_{CHA})	V_{IH}	2.4		V_{CC}	V
Low-Level Input Voltage ($\overline{STBY}$, V_{CHA})	V_{IL}	0		0.6	V
Receiver Input Voltage	R_{IN}	–30		+30	V
Operating Ambient Temperature	T_A	–40		+85	°C
Capacitance of External Capacitor	**Note 7**	0.33		4.7	μF

Note 7. In low temperature (below 0 ˚C), the capacitance of electrolytic capacitor becomes lower. Therefore, set higher values when using in low temperature.
Concerning the wiring length between the capacitor and the IC, the shorter the better.
Capacitors with good frequency characteristics such as tantalum capacitors, laminated ceramic capacitors, and aluminum electrolytic capacitors for switching power supply are recommended for the external capacitors.

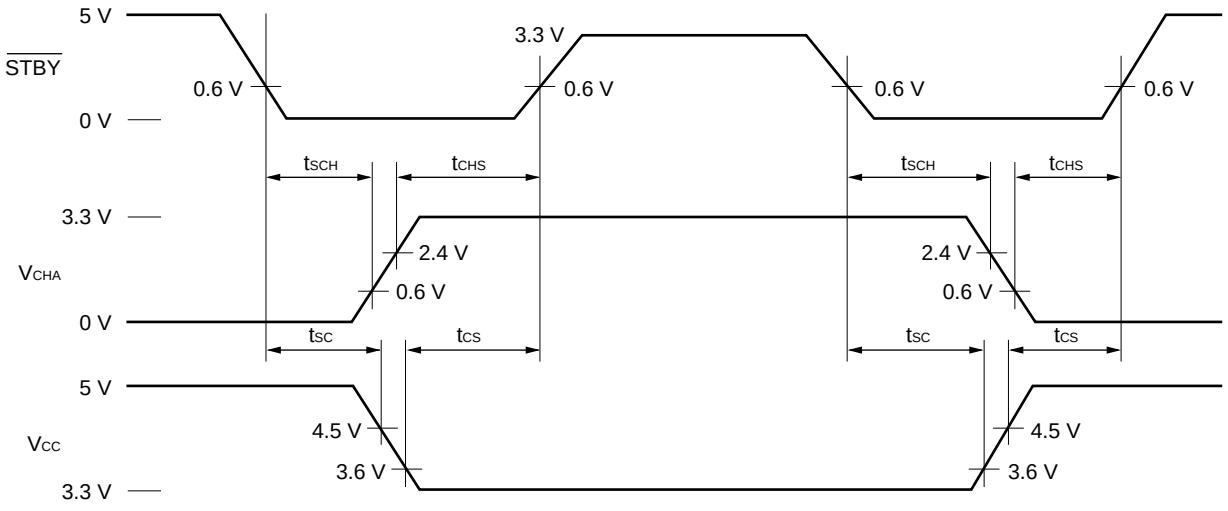
ELECTRICAL SPECIFICATIONS (TOTAL)

(Unless otherwise specified, T_A = –40 to +85 °C, C_1 to C_5 = 1 μF)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	I_{CC1}	V_{CC} = +3.3 V, No load, R_{IN} pin OPEN, $\overline{STBY}$ = H		6.5	13	mA
		V_{CC} = +5.0 V, No load, R_{IN} pin OPEN, $\overline{STBY}$ = H		4.5	9	mA
Circuit Current	I_{CC2}	V_{CC} = +3.3 V, R_L = 3 kΩ (D_{OUT}), D_{IN} = GND, R_{IN}, R_{OUT} pin OPEN, $\overline{STBY}$ = H		19	24	mA
		V_{CC} = +5.0 V,R_L = 3 kΩ (D_{OUT}), D_{IN} = GND, R_{IN}, R_{OUT} pin OPEN, $\overline{STBY}$ = H		14	18	mA
Circuit Current at Standby	I_{CC3}	V_{CC} = +3.3 V, No load, D_{IN} and R_{IN} pins are OPEN, $\overline{STBY}$ = L, T_A = 25 °C		1	3	μA
		V_{CC} = +3.3 V, No load, D_{IN} and R_{IN} pins are OPEN, $\overline{STBY}$ = L		5		μA
		V_{CC} = +5.0 V, No load, D_{IN} and R_{IN} pins are OPEN, $\overline{STBY}$ = L, T_A = 25 °C		2	5	μA
		V_{CC} = +5.0 V, No load, D_{IN} and R_{IN} pins are OPEN, $\overline{STBY}$ = L		10		μA
High-Level Input Voltage	V_{IH}	V_{CC} = +3.0 to +5.5 V, $\overline{STBY}$, V_{CHA} pin	2.4			V
Low-Level Input Voltage	V_{IL}	V_{CC} = +3.0 to +5.5 V, $\overline{STBY}$, V_{CHA} pin			0.6	V
High-Level Input Current	I_{IH}	V_{CC} = +5.5 V, V_I = +5.5 V, $\overline{STBY}$, V_{CHA} pin			1	μA
Low-Level Input Current	I_{IL}	V_{CC} = +5.5 V, V_I = 0 V, $\overline{STBY}$, V_{CHA} pin			–1	μA
Input Capacitance	C_{IN}	Driver input and receiver input V_{CC} = +3.3 V, for GND, f = 1 MHz			10	pF
		Driver input and receiver input V_{CC} = +5.0 V, for GND, f = 1 MHz			10	pF
$\overline{STBY}$ — V_{CHA} Time	t_{SCH}	V_{CC} = +3.0 to +5.5 V, $\overline{STBY}$ ↓ → V_{CHA}, **Note 8**	1			μs
V_{CHA} — $\overline{STBY}$ Time	t_{CHS}	V_{CC} = +3.0 to +5.5 V, V_{CHA} → $\overline{STBY}$ ↑, **Note 8**	1			μs
$\overline{STBY}$ — V_{CC} Time	t_{SC}	V_{CC} = +3.0 to +5.5 V, $\overline{STBY}$ ↓ → V_{CC}, **Note 8**	1			μs
V_{CC} — $\overline{STBY}$ Time	t_{CS}	V_{CC} = +3.0 to +5.5 V, V_{CC} → $\overline{STBY}$ ↑, **Note 8**	1			μs

***** The TYP. values are for reference at T_A = 25 °C.

Note 8. Measuring point



ELECTRICAL SPECIFICATIONS (DRIVER)

(Unless otherwise specified, T_A = –40 to +85 °C, C_1 to C_5 = 1 μF)

3 V mode (unless otherwise specified, V_{CHA} = H, V_{CC} = 3.0 to 3.6 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Low-Level Input Voltage	V_{IL}				0.8	V
High-Level Input Voltage	V_{IH}		2.0			V
Low-Level Input Current	I_{IL}	V_{CC} = +3.6 V, V_I = 0 V			–25	μA
High-Level Input Current	I_{IH}	V_{CC} = +3.6 V, V_I = 3.6 V			1.0	μA
Output Voltage	V_{DO}	V_{CC} = +3.3 V, R_L = ∞, T_A = 25 °C		±9.5		V
		V_{CC} = +3.3 V, R_L = 3 kΩ, T_A = T_{opt}	±5.0	±6.0		V
		V_{CC} = +3.0 V, R_L = 3 kΩ, T_A = +25 °C	±5.0			V
Output Short-Circuit Current	I_{SC}	V_{CC} = +3.3 V, for GND			±40	mA
Slew-Rate [Note 9]	SR	C_L = 10 pF, R_L = 3 to 7 kΩ	3.0		30	V/μs
		C_L = 2 500 pF, R_L = 3 to 7 kΩ	3.0		30	V/μs
Propagation Delay Time [Note 9]	t_{PHL} t_{PLH}	R_L = 3 kΩ, C_L = 2 500 pF		2.5		μs
Output Resistor	R_O	V_{CC} = V_{DD} = V_{SS} = 0 V V_{OUT} = ±2 V	300			Ω
Standby Output Transfer Time	t_{DAZ}	R_L = 3 kΩ, C_L = 2 500 pF, [Note 10]		4	10	μs
Standby Output Transfer Time	t_{DZA}	R_L = 3 kΩ, C_L = 2 500 pF, [Note 10]		1	3	ms
Power-On Output Transfer Time	t_{PRA}	R_L = 3 kΩ, C_L = 2 500 pF, [Note 11]		1	3	ms

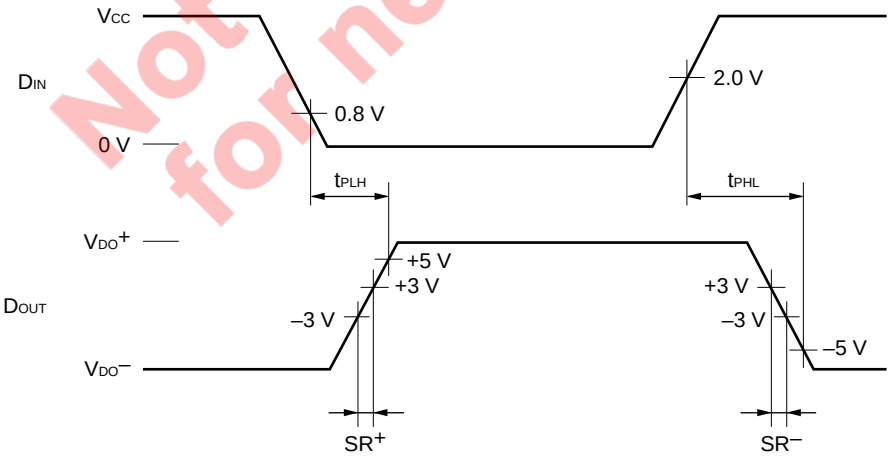
***** The TYP. values are for reference at T_A = 25 °C.

5 V mode (Unless otherwise specified, V_{CHA} = L, V_{CC} = +5.0 V ± 10 %)

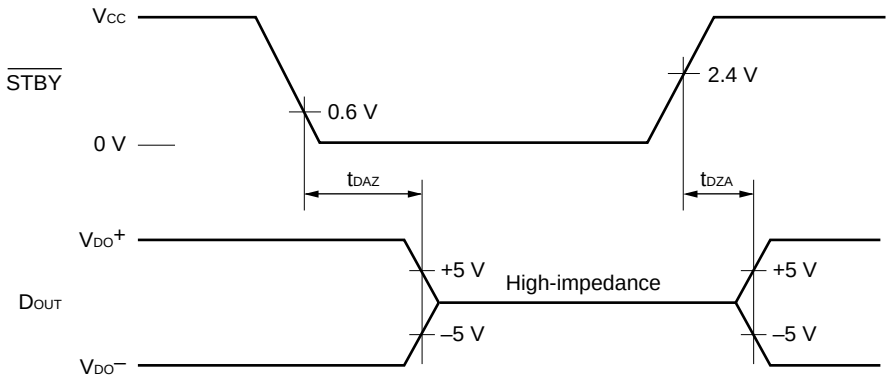
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Low-Level Input Voltage	V_{IL}				0.8	V
High-Level Input Voltage	V_{IH}		2.0			V
Low-Level Input Current	I_{IL}	V_{CC} = +5.5 V, V_I = 0 V			–40	μA
High-Level Input Current	I_{IH}	V_{CC} = +5.5 V, V_I = 5.5 V			1.0	μA
Output Voltage	V_{DO}	V_{CC} = +5.0 V, R_L = ∞, T_A = 25 °C		±9.7		V
		V_{CC} = +5.0 V, R_L = 3 kΩ, T_A = T_{opt}	±6.0			V
		V_{CC} = +4.5 V, R_L = 3 kΩ, T_A = T_{opt}	±5.0			V
Output Short-Circuit Current	I_{SC}	V_{CC} = +5.0 V, for GND			±40	mA
Slew-Rate Note 9	SR	C_L = 10 pF, R_L = 3 to 7 kΩ	4.0		30	V/μs
		C_L = 2 500 pF, R_L = 3 to 7 kΩ	4.0		30	V/μs
Propagation Delay Time Note 9	t_{PHL} t_{PLH}	R_L = 3 kΩ, C_L = 2 500 pF		2		μs
Output Resistor	R_O	V_{CC} = V_{DD} = V_{SS} = 0 V V_{OUT} = ±2 V	300			Ω
Standby Output Transfer Time	t_{DAZ}	R_L = 3 kΩ, C_L = 2 500 pF, Note 10		4	10	μs
Standby Output Transfer Time	t_{DZA}	R_L = 3 kΩ, C_L = 2 500 pF, Note 10		0.5	1	ms
Power-On Output Transfer Time	t_{PRA}	R_L = 3 kΩ, C_L = 2 500 pF, Note 12		0.5	1	ms

***** The TYP. values are for reference at T_A = 25 °C.

Note 9. Measuring point

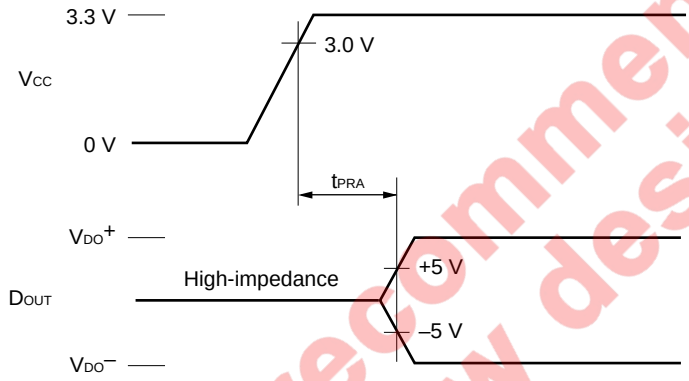


Note 10. Measuring point



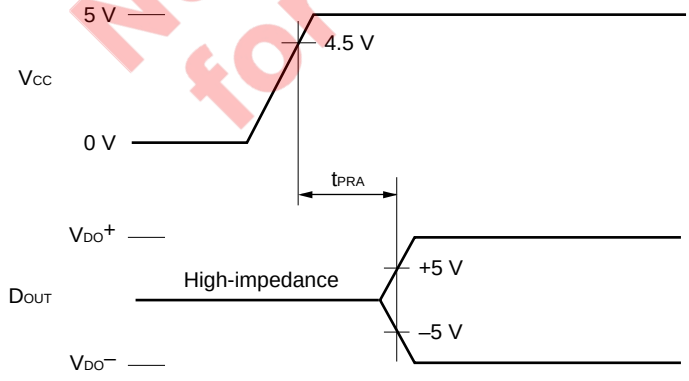
Driver outputs are indefinite during transition time (t_{DZA}).

Note 11. Measuring point



Driver outputs are indefinite during transition time (t_{PRA}).

Note 12. Measuring point



Driver outputs are indefinite during transition time (t_{PRA}).

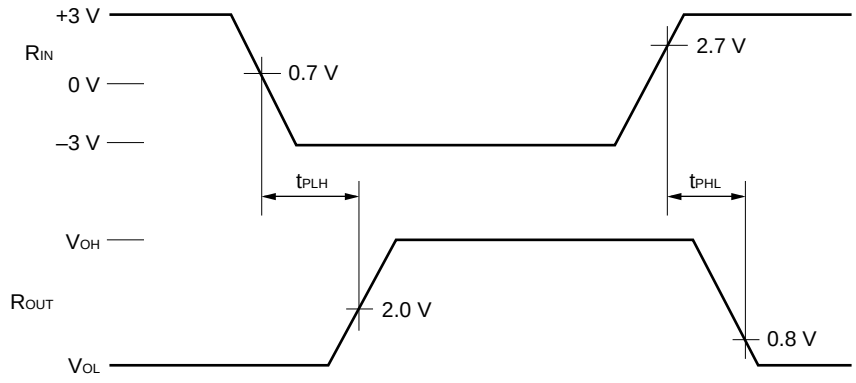
ELECTRICAL SPECIFICATIONS (RECEIVER)

(Unless otherwise specified, V_{CC} = 3.0 to 5.5 V, T_A = –40 to +85 °C, C_1 to C_5 = 1 μF)

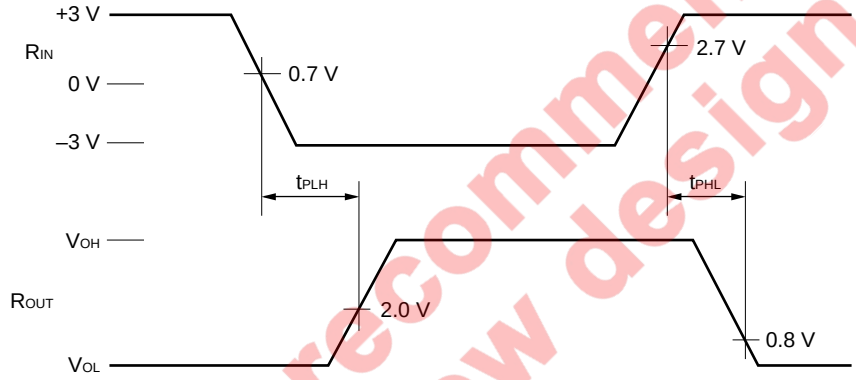
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Low-Level Output Voltage	V_{OL1}	I_{OUT} = 4 mA, $\overline{STBY}$ = H			0.4	V
High-Level Output Voltage	V_{OH1}	I_{OUT} = –4 mA, $\overline{STBY}$ = H	V_{CC} – 0.4			V
Low-Level Output Voltage	V_{OL2}	I_{OUT} = 4 mA, $\overline{STBY}$ = L			0.5	V
High-Level Output Voltage	V_{OH2}	I_{OUT} = –4 mA, $\overline{STBY}$ = L	V_{CC} – 0.5			V
Propagation Delay Time ($\overline{STBY}$ = H)	t_{PHL} t_{PLH}	$R_{IN} \rightarrow R_{OUT}$, C_L = 150 pF V_{CC} = +3.0 V, **Note 13**		0.2		μs
Input Resistor	R_I		3	5.5	7	kΩ
Input Pin Open Voltage	V_{IO}				0.5	V
Input Threshold ($\overline{STBY}$ = H)	V_{IH}	V_{CC} = +3.0 to +5.5 V	1.7	2.3	2.7	V
	V_{IL}	V_{CC} = +3.0 to +5.5 V	0.7	1.1	1.7	V
	V_H	V_{CC} = +3.0 to +5.5 V (Hysteresis width)	0.5	1.2	1.8	V
Standby Output Transfer Time	t_{DAH}	**Note 15**		0.2	3	μs
Standby Output Transfer Time	t_{DHA}	V_{CHA} = H (3 V mode) **Note 15**		0.6	3	ms
		V_{CHA} = L (5 V mode) **Note 15**		0.3	1	ms
Power-On Reset Release Time	t_{PRA}	V_{CHA} = H (3 V mode) **Note 16**		1	3	ms
		V_{CHA} = L (5 V mode) **Note 17**		0.5	1	ms

***** The TYP. values are for reference at T_A = 25 °C.

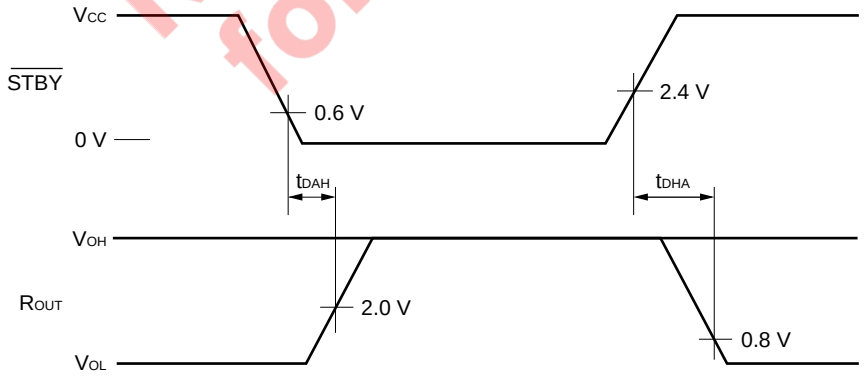
Note 13. Measuring point



Note 14. Measuring point

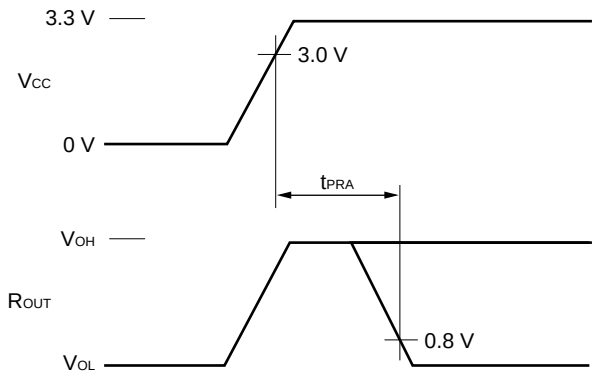


Note 15. Measuring point



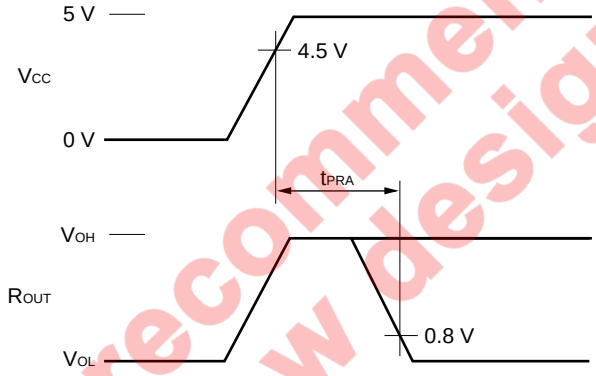
Receiver outputs are indefinite during transition time (t_{DHA}).

Note 16. Measuring point



Receiver outputs are indefinite during reset release time (t_{PRA}).

Note 17. Measuring point



Receiver outputs are indefinite during reset release time (t_{PRA}).

REFERENCE MATERIAL

- IC PACKAGE MANUAL (C10943X)
- NEC SEMICONDUCTOR DEVICE RELIABILITY/QUALITY (IEI-1212)

RECOMMENDED SOLDERING CONDITIONS

The following conditions (See table below) must be met when soldering this product.

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

TYPES OF SURFACE MOUNT DEVICE

For more details, refer to our document “SMT MANUAL” (C10535E).

μPD4721 GS-GJG

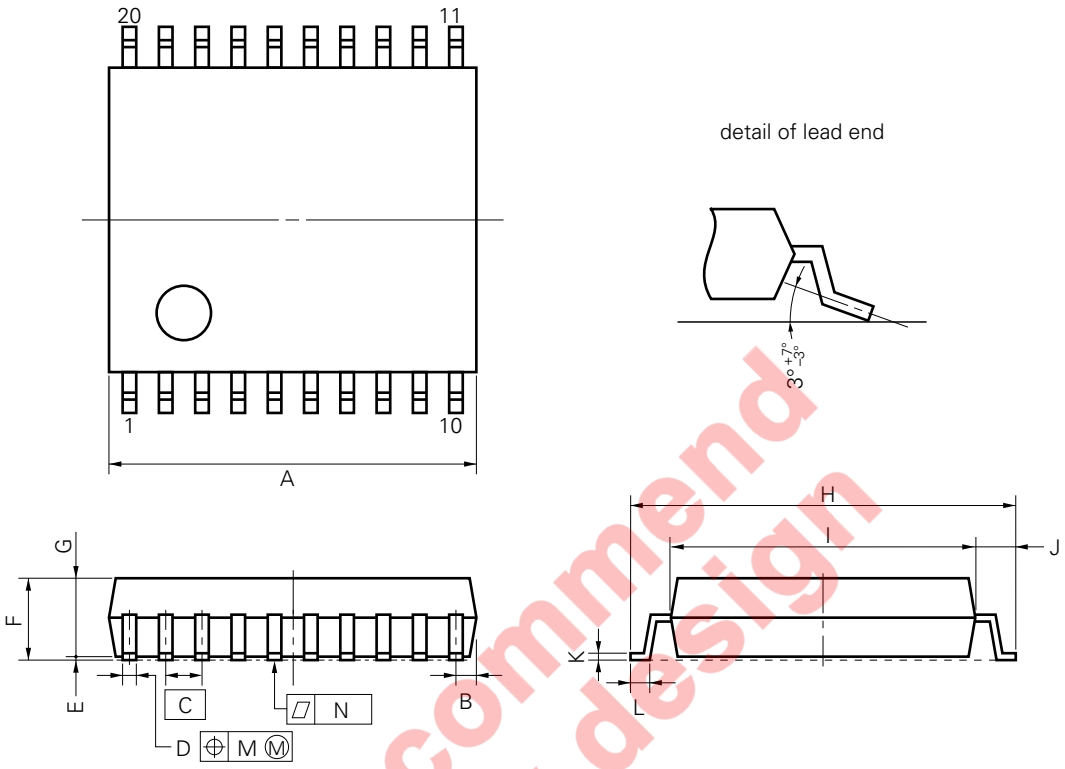
Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak package’s surface temperature: 230 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 2, Exposure limit*: None	IR30-00-2
VPS	Peak package’s surface temperature: 215 °C or below, Reflow time: 40 seconds or below (200 °C or higher), Number of reflow process: 2, Exposure limit*: None	VP15-00-2
Wave soldering	Solder Temperature: 260 °C or lower, Reflow time: Within 10 sec, Number of reflowprocess: 1, Exposure limit*: None	WS60-00-1
Partial heating method	Terminal temperature: 300 °C or below, Flow time: 10 seconds or below, Exposure limit*: None	◯

* Exposure limit before soldering after dry-pack package is opened.
Storage conditions: 25 °C and relative humidity at 65 % or less.

Note Do not apply more than a single process at once, except for “Partial heating method”

PACKAGE DRAWINGS

20 PIN PLASTIC SHRINK SOP (300 mil)



P20GM-65-300B-2

NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	7.00 MAX.	0.276 MAX.
B	0.575 MAX.	0.023 MAX.
C	0.65 (T.P.)	0.026 (T.P.)
D	0.30 ± 0.10	$0.012^{+0.004}_{-0.005}$
E	0.125 ± 0.075	0.005 ± 0.003
F	2.0 MAX.	0.079 MAX.
G	1.7	0.067
H	8.1 ± 0.3	0.319 ± 0.012
I	6.1 ± 0.2	0.240 ± 0.008
J	1.0 ± 0.2	$0.039^{+0.009}_{-0.008}$
K	$0.15^{+0.10}_{-0.05}$	$0.006^{+0.004}_{-0.002}$
L	0.5 ± 0.2	$0.020^{+0.008}_{-0.009}$
M	0.12	0.005
N	0.10	0.004

[MEMO]

[MEMO]

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While NEC Corporation has been making continuous effort to enhance the reliability of its semiconductor devices, the possibility of defects cannot be eliminated entirely. To minimize risks of damage or injury to persons or property arising from a defect in an NEC semiconductor device, customers must incorporate sufficient safety measures in its design, such as redundancy, fire-containment, and anti-failure features.

NEC devices are classified into the following three quality grades:

"Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.

- Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
- Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
- Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.